



## CMOS-MEMS Fabrication Technologies and Devices

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### Message from the Guest Editors

Dear Colleagues,

Electronics are extremely popular in our daily life. Semiconductors such as complementary metal oxide semiconductor (CMOS) and micro-electro-mechanical system (MEMS) are key devices in the electronic field. CMOS can be integrated with MEMS components within a single chip (3D integration) to produce compact and low-cost CMOS-MEMS devices for multiple applications (chemical sensing, energy harvesting, signal transmission, and others). Therefore, these devices' fabrication and integration are essential for the development of the society. This Special Issue aims to gather high quality research contributions dealing with MEMS devices integrated with CMOS, independently of fabrication technologies and final applications.

Deadline for manuscript  
submissions:

**closed (20 January 2023)**





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